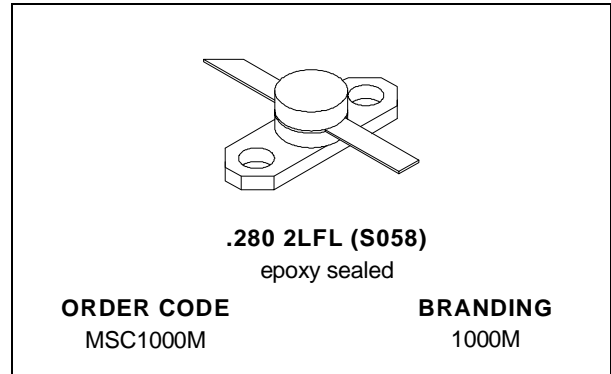


RF & MICROWAVE TRANSISTORS AVIONICS APPLICATIONS

- RUGGEDIZED VSWR $\infty:1$
- INPUT MATCHING
- LOW THERMAL RESISTANCE
- CLASS A OPERATION
- $P_{OUT} = 0.6 \text{ W MIN. WITH } 10.8 \text{ dB GAIN}$

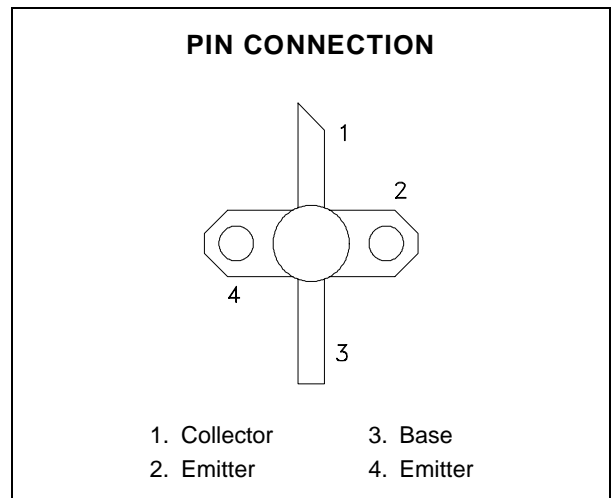


DESCRIPTION

The MSC1000M is a Class A, common emitter transistor with an emitter ballasted Matrix geometry specifically designed for DME/IFF driver applications.

This device is capable of withstanding a $\infty:1$ load VSWR at any phase angle under full rated conditions. Low RF thermal resistance and semi-automatic wire bonding techniques ensure high reliability and product consistency.

The MSC1000M is housed in the IMPAC™ package with internal input matching.



ABSOLUTE MAXIMUM RATINGS ($T_{case} = 25^{\circ}\text{C}$)

Symbol	Parameter	Value	Unit
P_{DISS}	Power Dissipation* (See Safe Area)	—	W
I_C	Device Current*	300	mA
V_{CE}	Collector-Emitter Bias Voltage*	20	V
T_J	Junction Temperature (Pulsed RF Operation)	200	$^{\circ}\text{C}$
T_{STG}	Storage Temperature	- 65 to +150	$^{\circ}\text{C}$

THERMAL DATA

$R_{TH(j-c)}$	Junction-Case Thermal Resistance*	35	$^{\circ}\text{C/W}$
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*Applies only to rated RF amplifier operation

MSC1000M

ELECTRICAL SPECIFICATIONS ($T_{case} = 25^{\circ}C$)

STATIC

Symbol	Test Conditions		Value			Unit
			Min.	Typ.	Max.	
BV_{CBO}	$I_C = 1mA$	$I_E = 0mA$	50	—	—	V
BV_{EBO}	$I_E = 1mA$	$I_C = 0mA$	3.5	—	—	V
BV_{CEO}	$I_C = 5mA$	$I_B = 0mA$	20	—	—	V
I_{CES}	$V_{CE} = 28V$		—	—	1.0	mA
h_{FE}	$V_{CE} = 5V$	$I_C = 100mA$	15	—	120	—

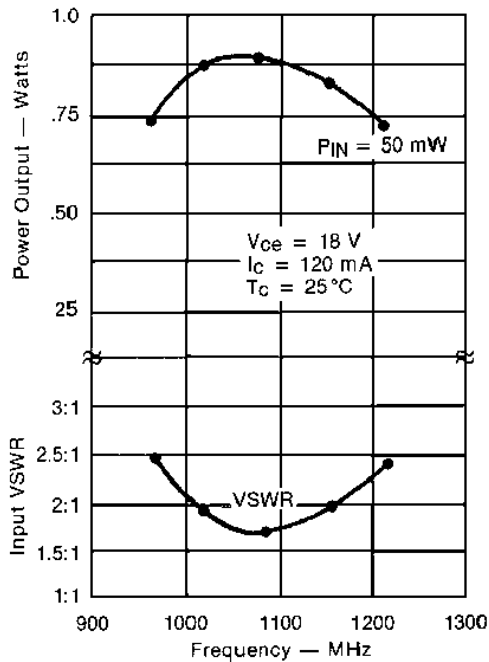
DYNAMIC

Symbol	Test Conditions			Value			Unit
				Min.	Typ.	Max.	
P_{OUT}	$f = 1025 - 1150 MHz$	$P_{IN} = 50 mW$	$V_{CE} = 18 V$	0.6	0.85	—	W
G_P	$f = 1025 - 1150 MHz$	$P_{IN} = 50 mW$	$V_{CE} = 18 V$	10.8	12.3	—	dB

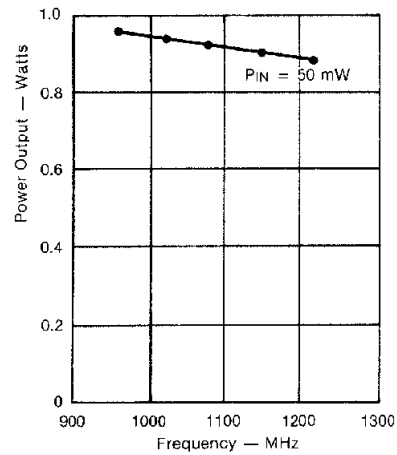
Note: Pulse Width = $10\mu Sec$ $I_C = 120mA$
 Duty Cycle = 1%

TYPICAL PERFORMANCE

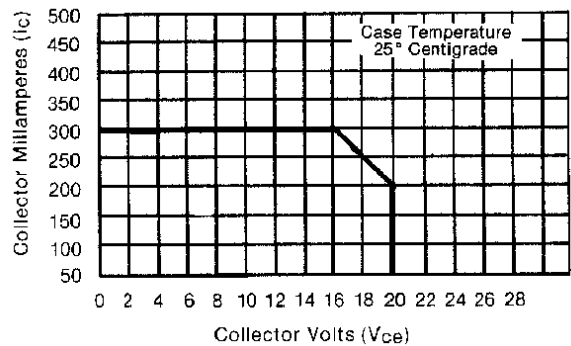
BROADBAND POWER AMPLIFIER



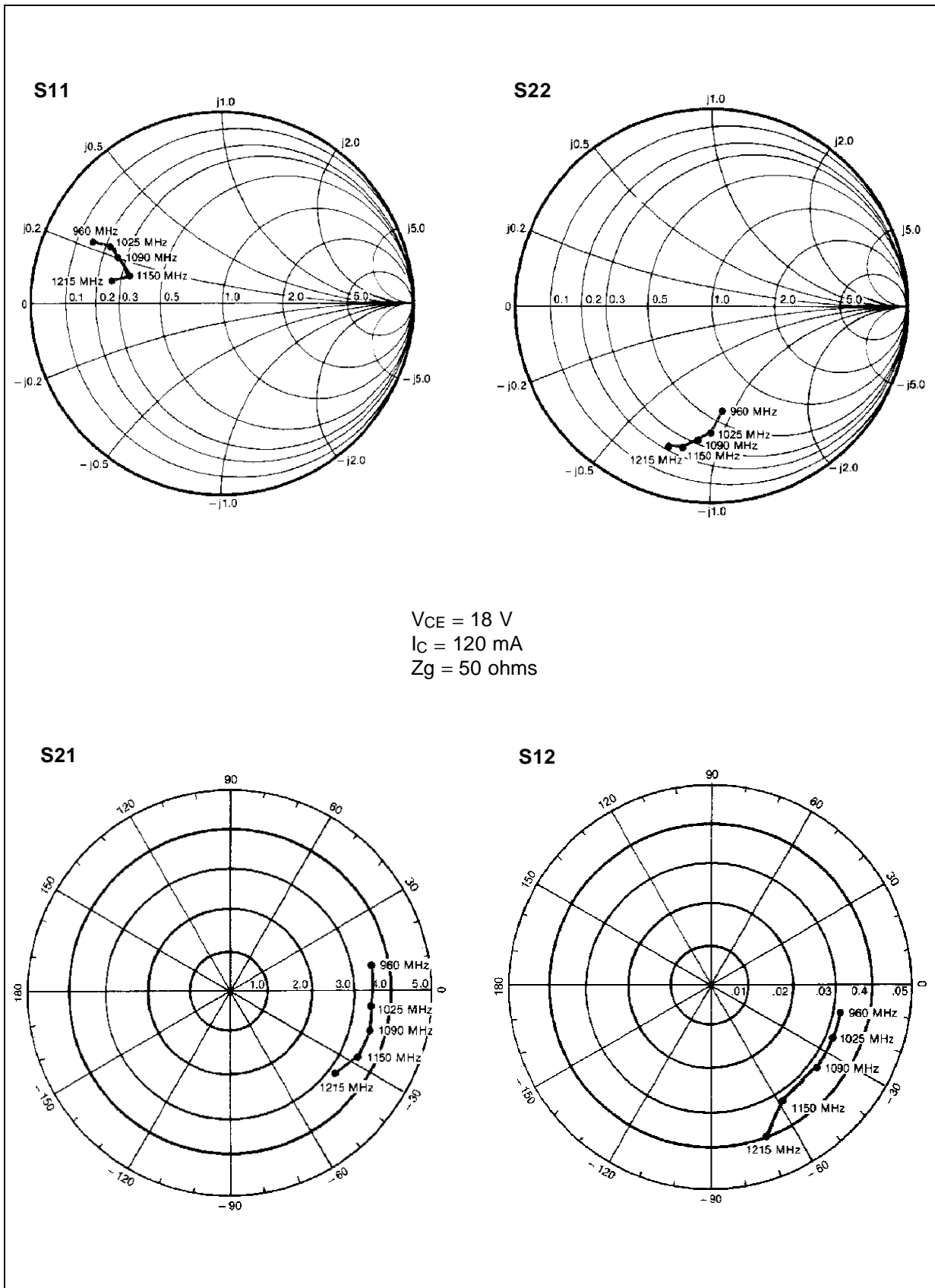
NARROWBAND POWER OUTPUT vs FREQUENCY



MAXIMUM OPERATING AREA for FORWARD BIAS OPERATION



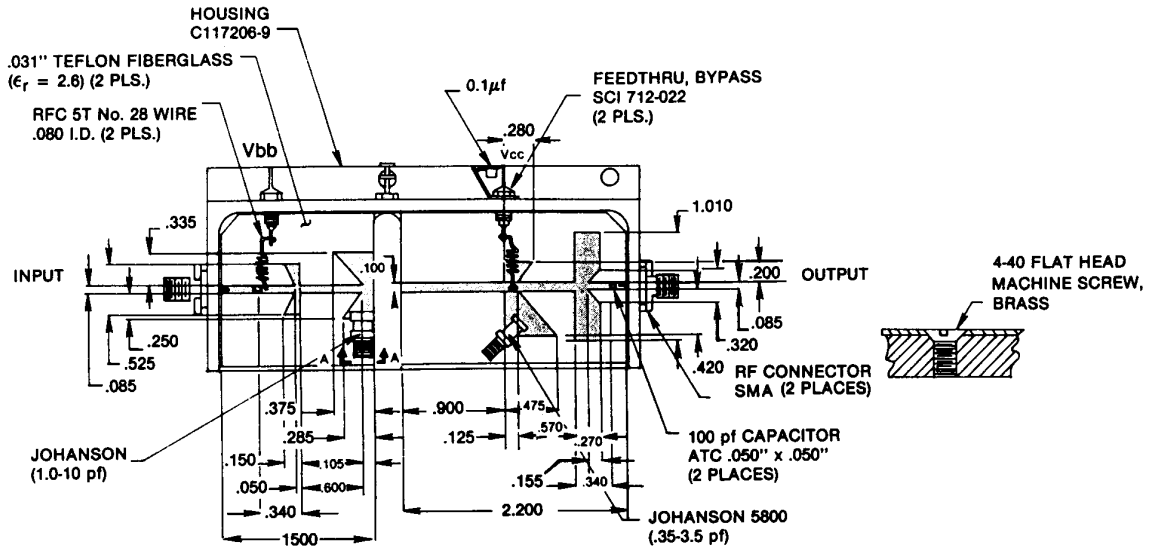
TYPICAL S-PARAMETERS



MSC1000M

TEST CIRCUIT

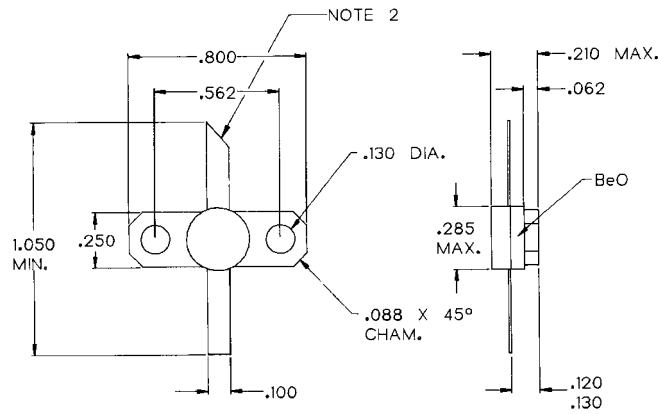
Ref.: Dwg No. C127297



All dimensions are in inches.

PACKAGE MECHANICAL DATA

Ref.: Dwg. No.: J135039B



- NOTES:
1. ALL TOLERANCE $\pm .010$ EXCEPT WHERE NOTED; DIMENSIONS IN INCHES.
 2. COLLECTOR LEAD SLANT CUT.

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